

Zener Diode DZ5S120D0R

DZ5S120D0R Silicon epitaxial planar type

For surge absorption circuit DZ5J120D in SSMini5 type package

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance RzHalogen-free / RoHS compliant
 - (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol:05
- Basic Part Number : Dual DZ3X120D (Common anode)

Packaging Embossed type (Thermo-compression sealing) 8 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

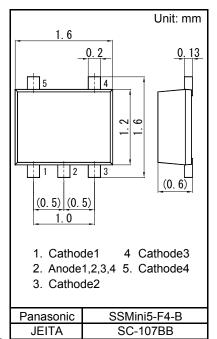
Parameter	Symbol	Rating	Unit	
Total power dissipation ^{*1}	PT	150	mW	
Electrostatic discharge *2	ESD	±10	kV	
Junction temperature	Tj	150	°C	
Operating ambient temperature	Topr	-40 to +85	°C	
Storage temperature	Tstg	-55 to +150	°C	

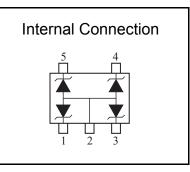
Storage temperatureTstg-55 to +150Note) *1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)

(4Diode total)

Solder in (0.35 mm x 0.40 mm)

*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)





SOT-665

Code

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit		
Forward voltage	VF	IF = 10 mA			1.0	V		
Zener voltage *1, *2	VZ	IZ = 5 mA	11.40		12.60	V		
Zener operating resistance	RZ	IZ = 5 mA			30	Ω		
Zener rise operating resistance	RZK	IZ = 0.5 mA			80	Ω		
Reverse current	IR	VR = 9 V			0.05	μA		
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		8.5		mV/°C		

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. *1: The temperature must be controlled 25°C for VZ mesurement.

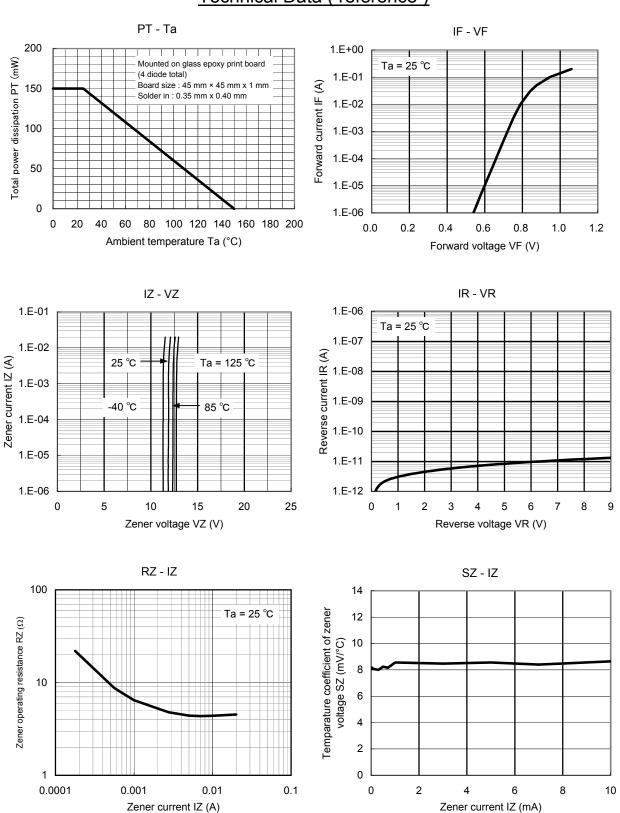
VZ value measured at other temperature must be adjusted to VZ (25°C)

*2: VZ guaranted 20 ms after current flow.

*3: Tj = 25°C to 150°C



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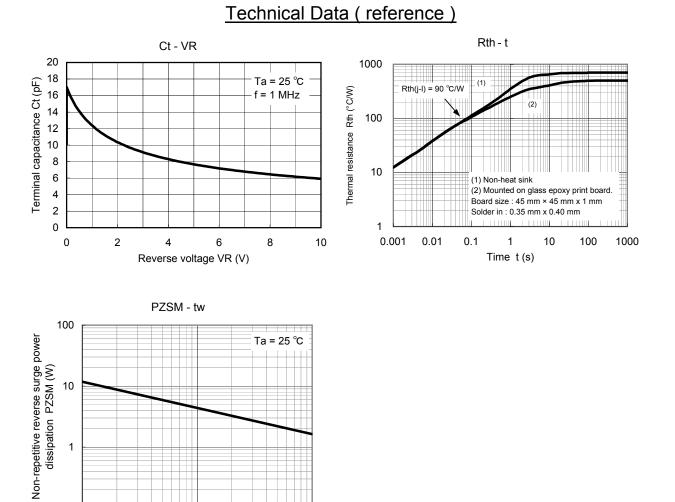
Technical Data (reference)

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Established : 2010-08-05 Downloaderringehttp://www.datasheetcatalog.com/



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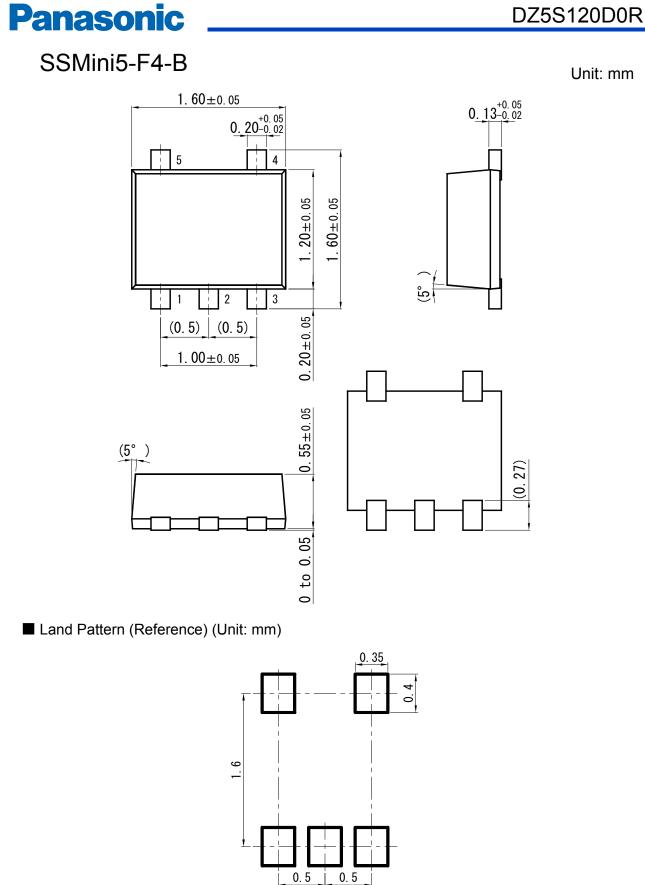


10000

0.1 └ 100

1000

Pulse width tw (µs)



Zener Diode

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